

WHAT IS CLAIMED IS:

1. An apparatus comprising:
an integrated circuit package substrate;
a plurality of integrated circuit die attached to the integrated circuit package
5 substrate; and
a stiffener strip attached to the integrated circuit package substrate and surrounding
two or more of the plurality of integrated circuit die.
2. An apparatus according to Claim 1, further comprising:
10 underfill material disposed between the plurality of integrated circuit die and the
integrated circuit package substrate.
3. An apparatus comprising:
an integrated circuit package;
15 an integrated circuit die coupled to the integrated circuit package; and
a stiffener portion coupled to the integrated circuit package and surrounding the
integrated circuit die.
4. An apparatus according to Claim 3, further comprising:
20 underfill material disposed between the integrated circuit die and the integrated
circuit package.
5. An apparatus according to Claim 3, wherein the stiffener portion and the
integrated circuit package define a well in which the integrated circuit die is disposed, the
25 apparatus further comprising:

thermally-conductive material disposed in the well and in contact with the integrated circuit die.

6. An apparatus according to Claim 5, further comprising:
- 5 a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material.

7. A method comprising:
- placing a plurality of integrated circuit die on respective ones of a plurality of
- 10 mounting locations of an integrated circuit package substrate; and
- placing a stiffener strip defining a plurality of openings on the integrated circuit package substrate,
- wherein the plurality of integrated circuit die and the plurality of mounting locations are disposed in respective ones of the plurality of openings.

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8. A method according to Claim 7, further comprising:
- soldering the plurality of integrated circuit die to the respective mounting locations.

9. A method according to Claim 8, further comprising:
- 20 dispensing underfill material on the integrated package substrate adjacent to one or more of the mounting locations.

10. A method according to Claim 7, further comprising:
- singulating one of the plurality of integrated circuit die and a respective mounting
- 25 location of the integrated package substrate.

11. A system comprising:

a microprocessor comprising:

an integrated circuit package;

5 an integrated circuit die coupled to the integrated circuit package; and

a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die; and

a double data rate memory electrically coupled to the microprocessor.

10 12. A system according to Claim 11, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed, the microprocessor further comprising:

thermally-conductive material disposed in the well and in contact with the integrated circuit die.

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13. A system according to Claim 12, the microprocessor further comprising:

a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material.

20 14. A system according to Claim 11, further comprising:

a motherboard electrically coupled to the microprocessor and to the memory.